



October 31, 2005

PCN Number: 0513

PCN Change Level: Major

Subject: Qualification of new mold compound and die attach material at STATSChipPAC, Singapore for TQFP packages containing lead and RoHS compliant devices for SX-A and eX product families

Dear Purchasing,

This notice is to inform you that Actel has qualified the Abelstik 3230 die attach material and Sumitomo G700E "green" mold compound at STATSChipPAC for the SX-A and eX products that contain lead.

Actel has also qualified STATSChipPAC, located in Singapore, for assembly of RoHS-compliant TQFP packages for SX-A and eX devices listed in Table 1. RoHS-compliant devices are designated with a G in the package nomenclature.

Table 1: Affected Devices

Device	Package	RoHS-Compliant
A54SX32A	TQ144	
A54SX32A	TQ100	
A54SX16A	TQ144	
A54SX16A	TQ100	
A54SX08A	TQ144	
A54SX08A	TQ100	
eX256	TQ100	
eX128	TQ100	
eX128	TQ64	
eX64	TQ100	
eX64	TQ64	
A54SX32A	TQG176	✓
A54SX32A	TQG144	✓
A54SX32A	TQG100	✓
A54SX16A	TQG144	✓
A54SX16A	TQG100	✓
A54SX08A	TQG144	✓
A54SX08A	TQG100	✓



Table 1: Affected Devices

Device	Package	RoHS-Compliant
eX256	TQG100	✓
eX128	TQG100	✓
eX128	TQG64	✓
eX64	TQG100	✓
eX64	TQG64	✓

For both cases, the assembly location country, which is Singapore, is marked on the bottom of the device. For the changes highlighted in this PCN, Actel will begin shipping units from STATSChipPAC 90 days after the date of this letter. Included in this notification is qualification summary PA-062 for standard products and PA-064 for RoHS compliant devices.

For questions and to request a qualification report, please contact the Actel Technical Support hotline at tech@actel.com.

Regards,

Actel Corporation